

1 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

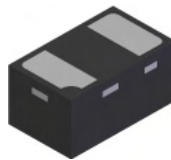
Features

- IEC 61000-4-2 (ESD): Air $\pm 15\text{kV}$, Contact $\pm 8\text{kV}$
- 1 Channel of ESD Protection
- Low Channel Input Capacitance of 0.85pF Typical
- Low Profile Package (0.53mm max) and Ultra-small PCB Footprint Area (1.08 * 0.68mm max) Suitable for Compact Portable Electronics
- Typically Used at High Speed Ports such as USB 2.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

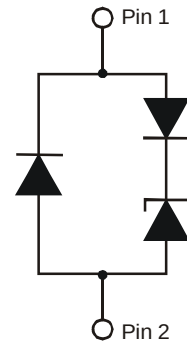
Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 **e4**
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Bottom View



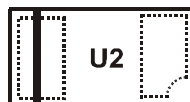
Device Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
D1213A-01LP-7B	X1-DFN1006-2	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



Top View

U2 = Product Type Marking Code
Line Denotes Pin 1 or Cathode Side

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I _{PP}	5	A	8/20μs, Per Figure 3
ESD Protection – Contact Discharge	V _{ESD_Contact}	±8	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD_Air}	±15	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse working voltage	V _{RWM}	—	—	3.3	V	—
Reverse current (Note 6)	I _R	—	0.1	1.0	μA	V _R = V _{RWM} = 3.3V
Reverse breakdown voltage	V _{BR}	6.0	—	—	V	I _R = 1mA
Forward voltage	V _F	0.6	0.8	0.95	V	I _F = 8mA
Reverse clamping voltage, Positive Transients	V _{CL1}	—	10.0	—	V	I _{PP} = 1A, t _p = 8/20μs
Reverse clamping voltage, Negative Transients	V _{CL2}	—	-1.7	—	V	I _{PP} = -1A, t _p = 8/20μs
Dynamic resistance	R _{DYN}	—	0.9	—	Ω	I _R = 1A, t _p = 8/20μs
Capacitance	C _T	—	0.85	1.2	pF	V _R = 1.65V, f = 1MHz

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.
 7. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destdtools/appnote_dnote.html.

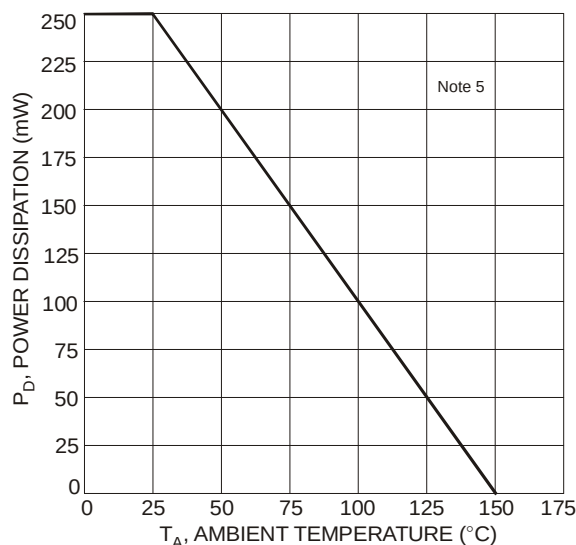


Figure 1 Power Derating Curve

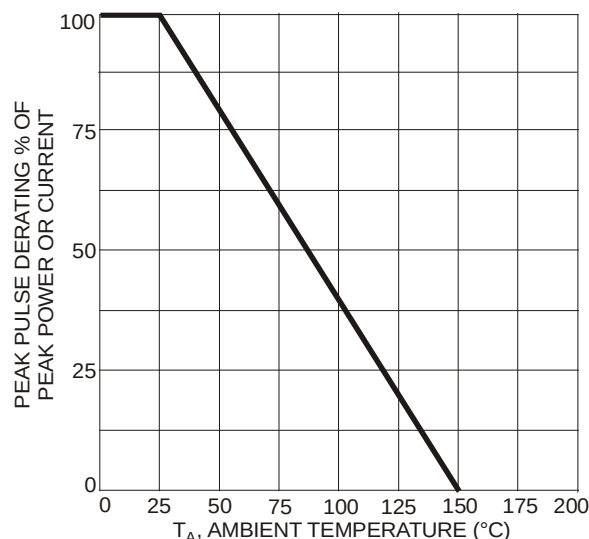


Figure 2 Pulse Derating Curve

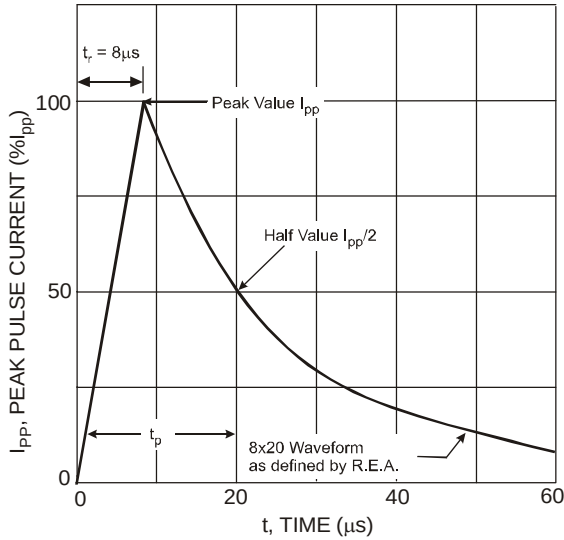


Figure 3 Pulse Waveform

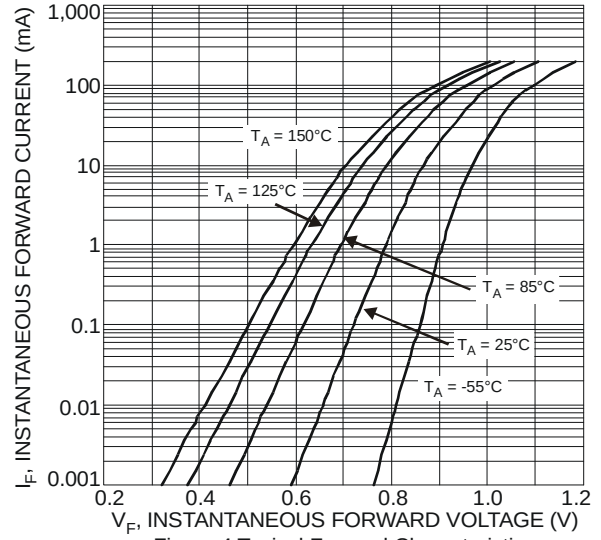


Figure 4 Typical Forward Characteristics

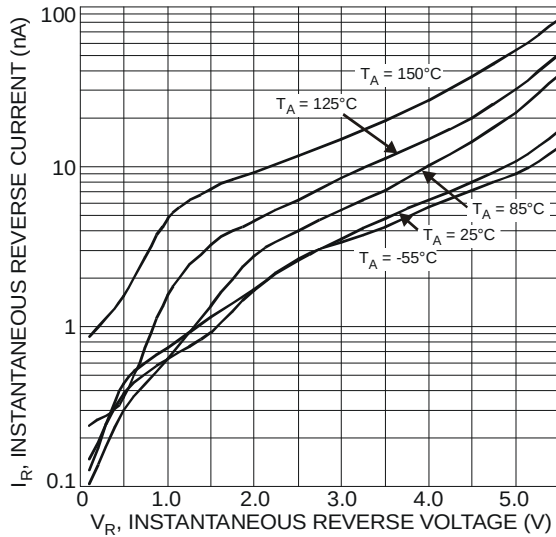


Figure 5 Typical Reverse Characteristics

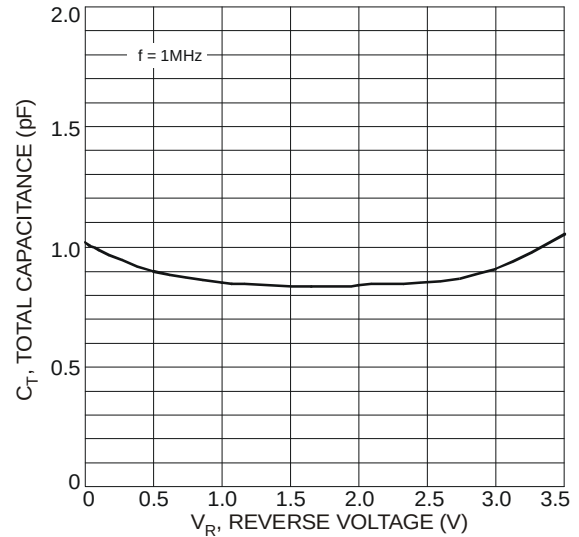
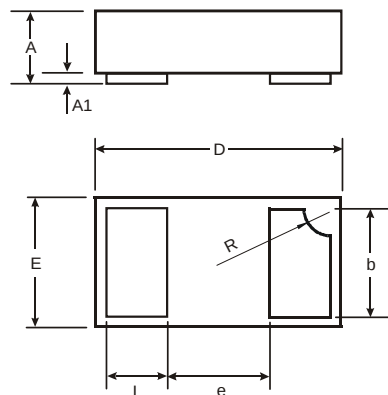


Figure 6 Typical Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

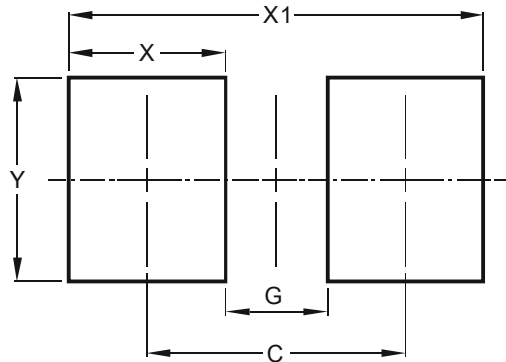
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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